



Low COO PVD solutions addressing 2.5D and 3D packaging challenges.

Abstract:

As with any emerging technology, 2.5D and 3D IC packaging integration brings new challenges. Amongst others, we will review thin wafer handling, organic passivation contact resistance control, glue layers critical thermal management and TSV high aspect ratio challenges. We will then demonstrate how Oerlikon's PVD technology has managed to address each of these issues with manufacturing low COO solutions.

Biography:

Patrick Desjardins has over twenty years of experience in the semicon industry. He is now the Asia product marketing manager for Oerlikon Systems. He has managed various roles from wafer fab yield enhancement and integration manager to metrology and defect inspection or plating sales and marketing roles. Patrick holds a MS Chemistry physics degree from Paris VI University as well as an engineering degree from the Ecole Nationale des Mines de Saint Etienne.